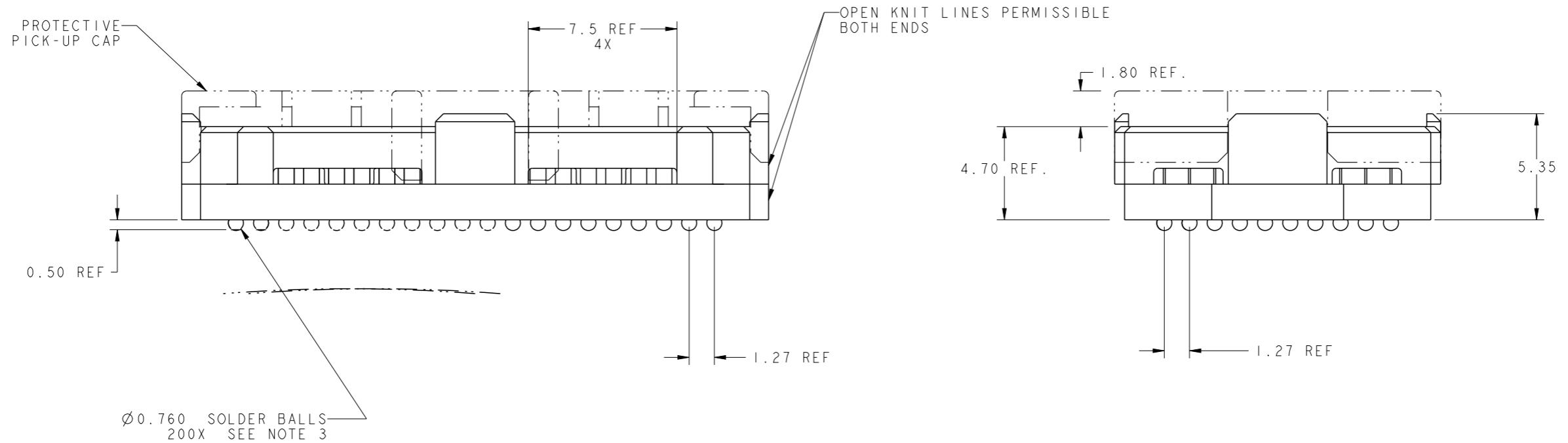
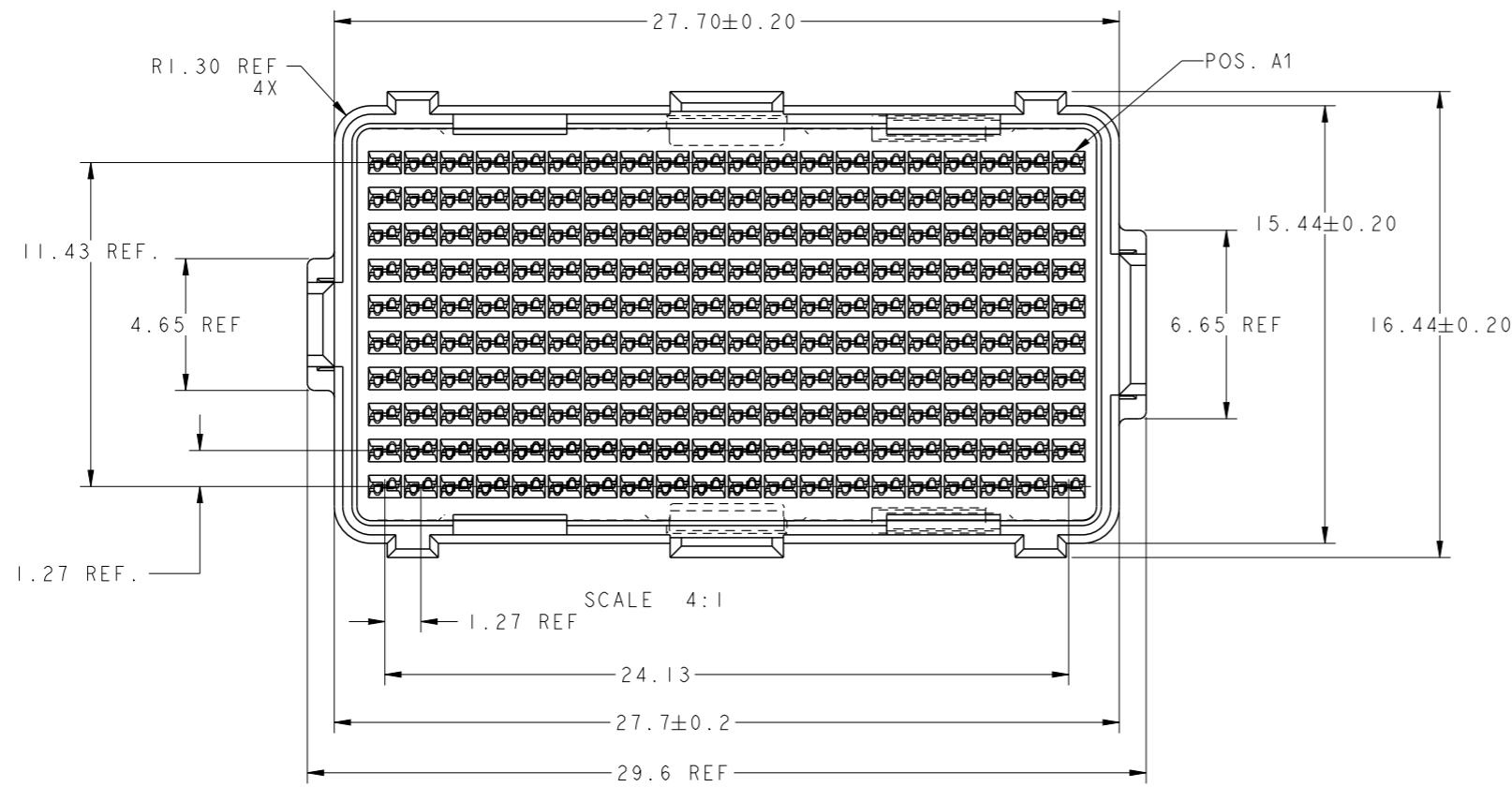
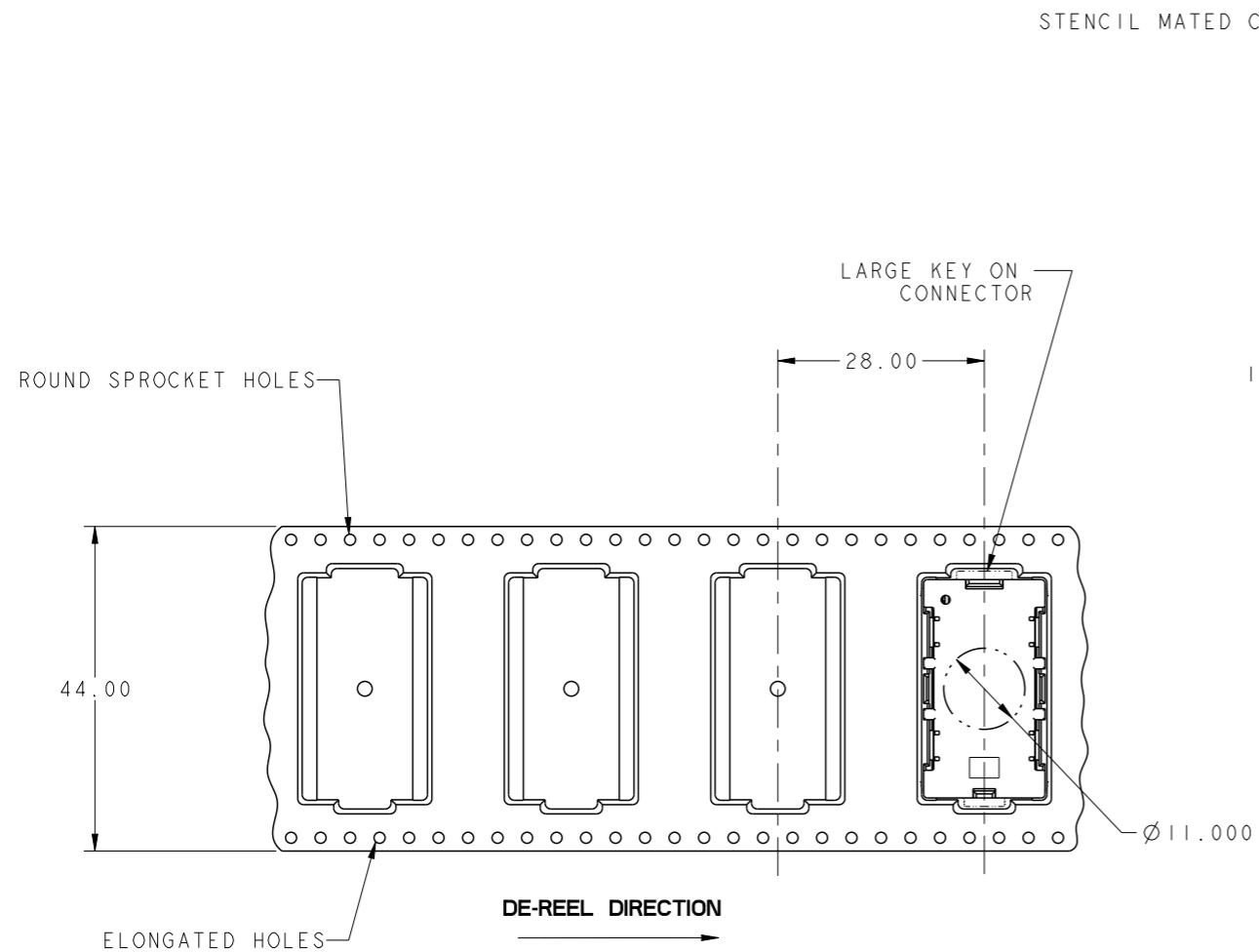


PRODUCT NUMBER: SEE SHEET 2

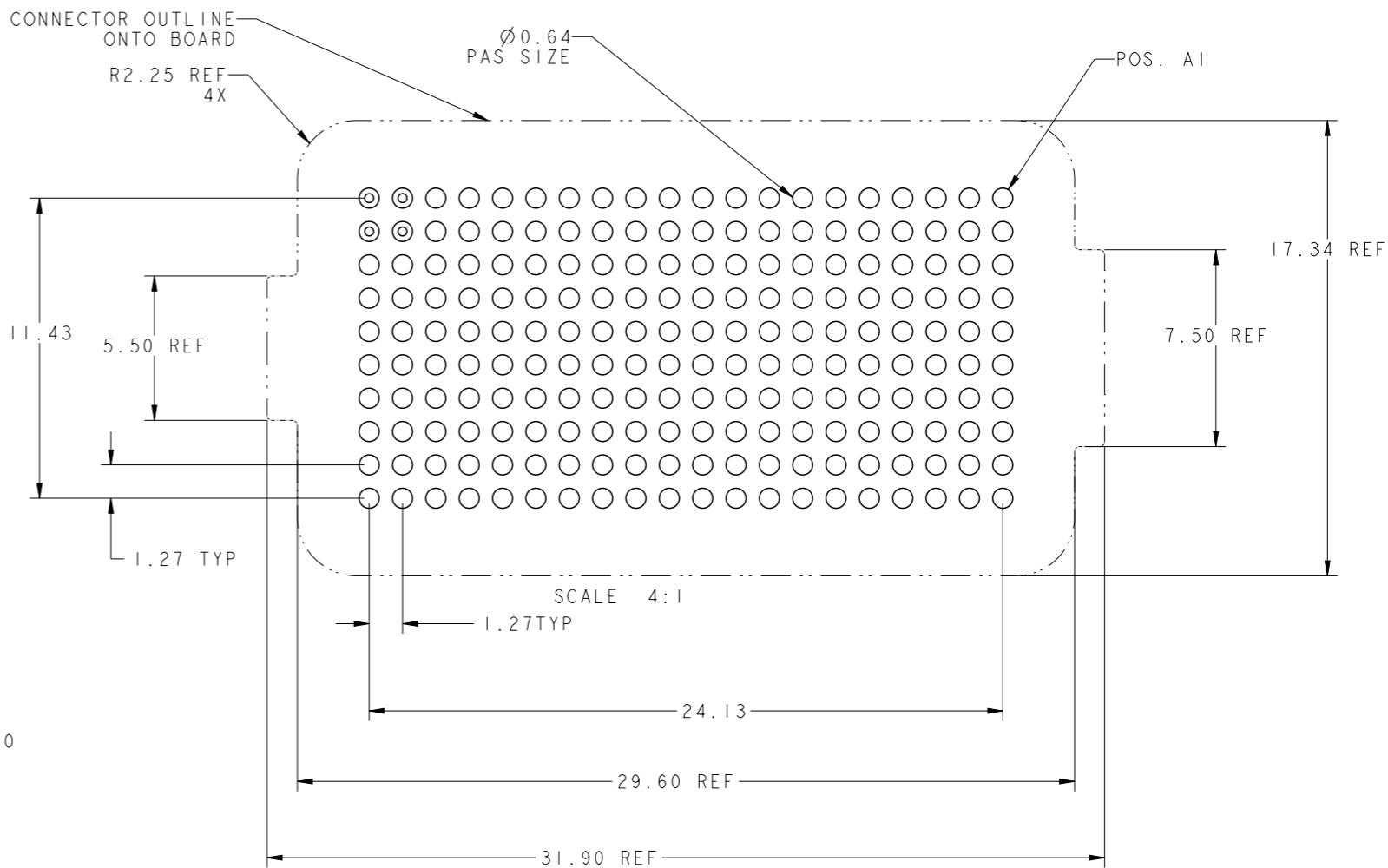


spec ref	dr	wcadmin	2001/08/01	projection	mm	size	A3	scale	2:1
tolerance std	eng	Dave Horchler	2013/01/22			ecn no	ELX-V-13917-1	rel level	Released
TOLERANCES UNLESS OTHERWISE SPECIFIED			chr						
surface	appr	R Marshall	2013/01/22	product family	MEG-ARRAY	rel level	Released		
linear	0.X	±.3			6.0mm RECPT. ASSY		dwg no	55724	rev
	0.XX	±.10	www.fci.com		10X20= 200 POS.				J
angular	0°	±°	cat. no.		Product - Customer Drw		sheet 1 of 3		

PRODUCT NO.	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
55724-001	YES	15u" (.38um) Au OVER Ni	SnPb
55724-001LF	YES	15u" (.38um) Au OVER Ni	SnAgCu LEAD FREE 6 7
55724-091	YES	15u" (.38um) GXT OVER Ni	SnPb
55724-091LF	YES	15u" (.38um) GXT OVER Ni	SnAgCu LEAD FREE 6 7
55724-101	YES	30u" (.76um) Au OVER Ni	SnPb
55724-101LF	YES	30u" (.76um) Au OVER Ni	SnAgCu LEAD FREE 6 7
55724-191	YES	30u" (.76um) GXT OVER Ni	SnPb
55724-191LF	YES	30u" (.76um) GXT OVER Ni	SnAgCu LEAD FREE 6 7
55724-201	YES	50u" (1.27um) Au OVER Ni	SnPb
55724-201LF	YES	50u" (1.27um) Au OVER Ni	SnAgCu LEAD FREE 6 7
55724-291	YES	50u" (1.27um) GXT OVER Ni	SnPb
55724-291LF	YES	50u" (1.27um) GXT OVER Ni	SnAgCu LEAD FREE 6 7



**TAPE & REEL PACKAGING**  
PER EIA 481-3



**BOARD PATTERN**

spec ref	dr	wcadmin	2001/08/01	projection	mm	size	A3	scale	2:1
tolerance std	eng	Dave Horchler	2013/01/22			ecn no	ELX-V-13917-1	rel level	Released
TOLERANCES UNLESS OTHERWISE SPECIFIED									
surface	linear	0.X	±.3		6.0mm RECPT. ASSY 10X20= 200 POS.	dwg no	55724	rev	J
		0.XX	±.10						
		0.XXX	±.050						
	angular	0°	±°	www.fci.com	cat. no.	Product - Customer Drw	sheet 2 of 3		

NOTES:

1. MATERIAL:  
HOUSING: LCP  
CONTACT: COPPER ALLOY

PLATING CONTACT: SEE TABLE ON SHEET I  
SOLDER BALL: SEE TABLE ON SHEET I  
EUTECTIC SnPb OR LEAD FREE  
95.5Sn/4Ag/0.5Cu

2. PLATING FOR -2XX SERIES DASH NOS:  
Au OVER Ni WITH SPECIAL CONTACT  
GEOMETRY TO MEET REQUIREMENTS  
OF TELCORDIA GR-1217-CORE:  
CENTRAL OFFICE ENVORONMENT.

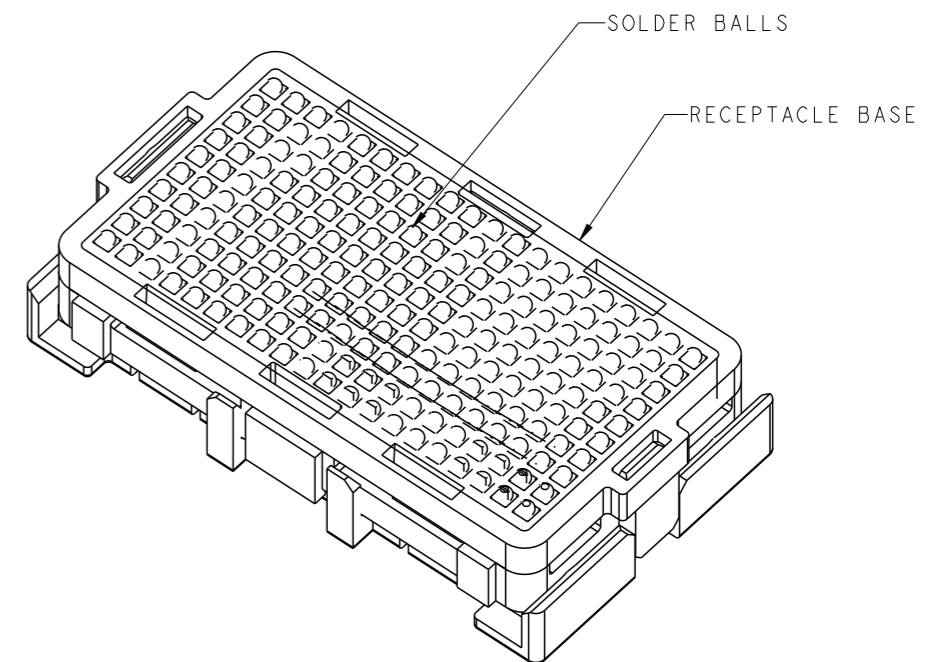
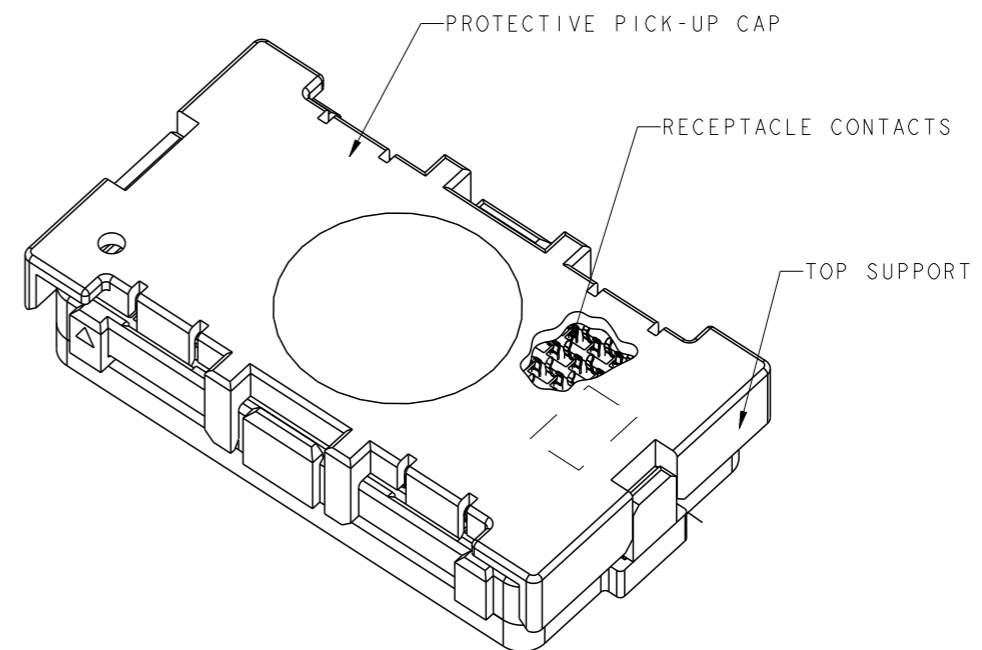
3. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE  
DUE TO REFLOW ATTACHMENT.

4. OVERALL BOARD-TO-BOARD STACK  
HEIGHT WHEN MATED TO:  
200 POSITION 0.0mm PLUG (84516) IS 6.0 REF.  
200 POSITION 6.0mm PLUG (84530) IS 12.0 REF.

5. SEE SK-47284 FOR MATING RESTRICTIONS  
WITH EARLIER DESIGN VERSIONS.

6. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION  
GS-20-033. LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY  
IN A LEADED SOLDER PROSESS DUE TO A HIGHER REFLOW TEMPERATURE  
LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH  
LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI  
FCI APPLICATION SPECIFICATION

7. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVE AND OTHER  
COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004. PRODUCT  
MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE  
NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH  
CHARACTER POSITION



spec ref		dr	wcadmin	2001/08/01	projection	mm	size	A3	scale	1:1				
tolerance std		eng	Dave Horchler	2013/01/22			ecn no		ELX-V-13917-1					
TOLERANCES UNLESS OTHERWISE SPECIFIED		chr	-	-			product family		MEG-ARRAY		rel level		Released	
surface		linear	0.X	±.3		title 6.0mm RECPT. ASSY 10X20= 200 POS.	dwg no 55724	rev J	www.fci.com		cat. no.	Product - Customer Drw	sheet 3 of 3	
			0.XX	±.10										
			0.XXX	±.050										
		angular	0°	±°										

